



23rd Annual Meeting of Members
March 20, 2025

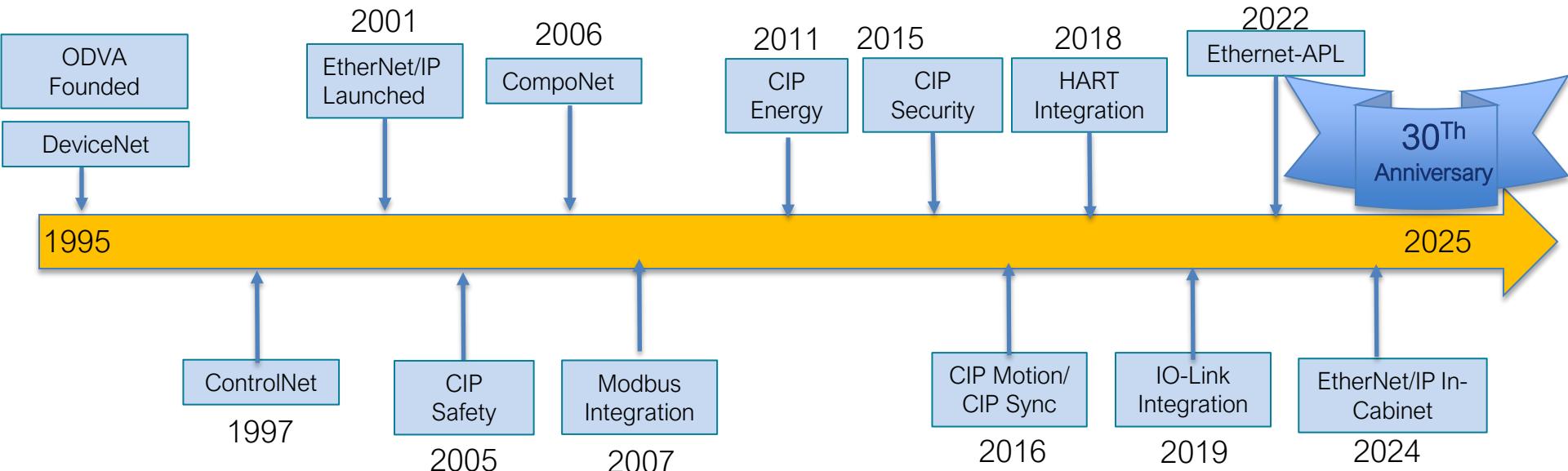
- Call to Order
- ODVA's 30 Year Journey
- Key Activities and Membership Update
- Technology Update
- Key Trends in Smart Manufacturing and Operational Resilience to Help Navigate Digital Transformation
- Introduction to Candidates for Election by the Regular Membership
- Election and Break
- Industry 4.0 Security: Protocols, Risks, Trends and Challenges
- Looking Ahead to the 24th Term
- Adjourn



ODVA's 30 Year Journey

Al Beydoun
President and Executive Director
ODVA

30 Years of Advancement in Technology



Behind ODVA's 30 Year Journey

Core Technologies and Continuous Enhancements:

- Core technologies that have provided solutions for Industrial Automation
- Evolving specifications that remained relevant in addressing industry challenges
- ODVA's robust certification and compliance process have facilitated global interoperability

Worldwide Adoption:

- Global membership contributing to the advancement of industrial automation across diverse sectors and regions.

Partnerships and Collaborations:

- ODVA's strategic collaborations and partnerships with other standard development organizations have enriched our initiatives and expanded our reach.

Members Contributions:

- Collective efforts of our members, whose commitment to innovation and interoperability have driven the widespread adoption of ODVA standards.



Leadership in the 23rd Term

Board of Directors



Dr. Rolf Birkhofer
Endress+Hauser



Mr. Jon DeSouza
HARTING



Mr. Toshiyuki Shigehisa
OMRON



Mr. Davis Mathews
Phoenix Contact



Mr. Scott Miller
Rockwell Automation



Mr. Thomas Petersen
Danfoss



Mr. Brian Reynolds
Honeywell



Mr. André Uhl
Schneider Electric



Technical Review Board

- Mr. Joakim Wiberg, Chair, ODVA (ex-officio)
- Mr. Raj Bandekar, Honeywell
- Mr. Torben Bertelsen, Danfoss
- Dr. Vivek R. Dave, HARTING
- Mr. Arulkumar Karuppanagounder, Schneider Electric
- Mr. Gregory Majcher, Rockwell Automation
- Mr. Kai Michel, Hilscher
- Mr. Toshiyuki Ozaki, OMRON
- Mr. Jörg Reinkensmeier, Endress+Hauser
- Dr. Al Beydoun, ODVA (ex-officio)
- Ms. Adrienne Meyer, ODVA (ex-officio)

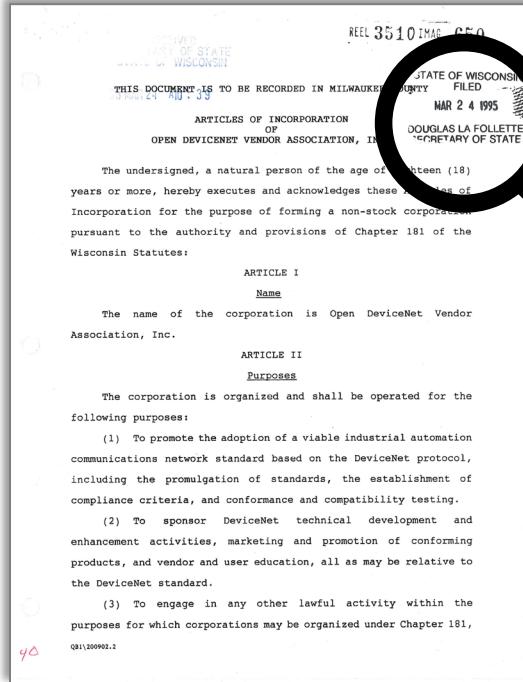
Market Advisory Committee

- Dr. Vivek Hajarnavis, Chair, Rockwell Automation
- Mr. Magnus Jansson, HMS Networks
- Mr. Arnold Offner, Phoenix Contact
- Mr. McKenzie Reed, HARTING
- Ms. Adriana Vargas, Honeywell
- Ms. Tonya Wyatt, Micro Motion (Emerson)
- Ms. Feiyan Zhao, Schneider Electric
- Dr. Al Beydoun, ODVA (ex-officio)
- Ms. Adrienne Meyer, ODVA (ex-officio)
- Mr. Steve Fales, ODVA (ex-officio)



Key Activities and Membership Update

**Adrienne Meyer
VP of Operations and Membership
ODVA**



Founded March 24, 1995

Celebrating our 30th Anniversary!



Founded for the purpose of promoting the adoption of DeviceNet including the promulgation of **standards**, establishment of **compliance criteria** and **conformance testing**.

DeviceNetTM



2025
ODVA

Industry Conference and 23rd Annual Meeting



475+ Attend ODVA Summit in Detroit, SEMICON/W 235 for DeviceNet Tutorials

Today, Michigan was the site for the first of what could be many ODVA sponsored DeviceNet Seminar and Product Demonstration Events. Targeted to local audiences, Local events may be more cost effective than national trade shows in North America for promoting DeviceNet. 375 participants attended the first day which featured the DeviceNet for Newcomers Course and a Table-top Exhibition with 34 ODVA Member Vendors. General Motors Control, Robotics and Wellness Group also brought their multi-vendor interoperability demonstration to the exhibition. It was originally built for the International Automotive Manufacturing Show in May.

The following day, 126 ODVA Engineers participated in one or more Special Interest Groups (SIGs). Nine SIGs are preparing new device profiles which will be included in the DeviceNet specifications after review by the ODVA System Architecture SG (see

inside...)

4th Annual Meeting May ODVA in OCA Pavilion GM Publishes Report on

(Continued on page 2)

Amy Boyd (facing camera) demonstrates table-top exhibit display

(Continued on page 2)

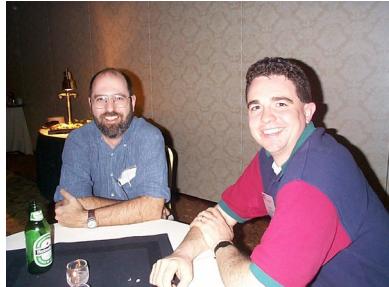
inside...

September '97 Catalog up to 220 Products
How do LonWorks and DeviceNet Connect
"No DNS Entry" - Fixing Netscape Errors

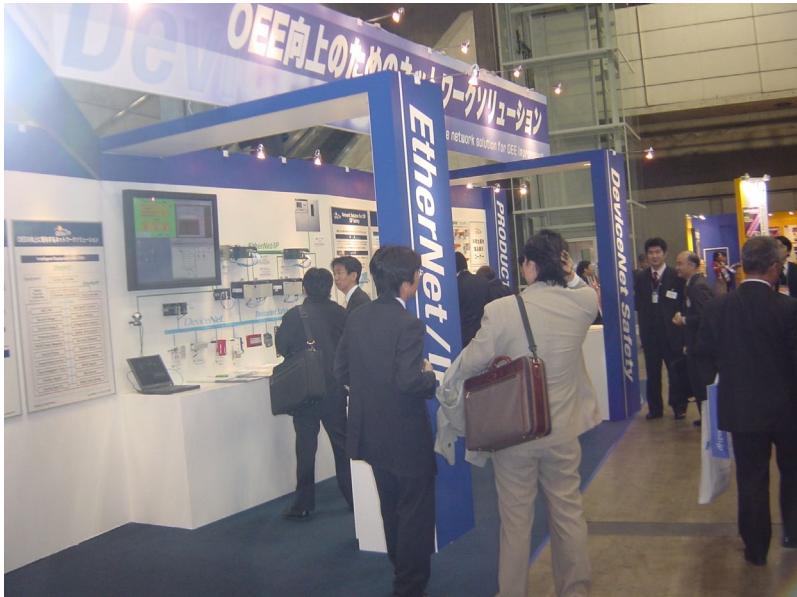
(Continued on page 2)

inside...

Celebrating our 30th Anniversary!



Celebrating our 30th Anniversary!



Celebrating 30 Years of ODVA Membership with us!

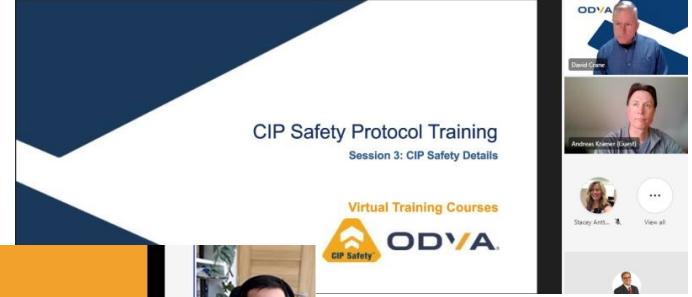
- SMC Corporation
- Yaskawa America, Inc.
- Eaton Electrical
- OMRON Corporation
- Parker Hannifin Corporation
- Rockwell Automation/Allen-Bradley
- Phoenix Contact
- Softing
- BALLUFF
- WAGO Corporation
- Festo SE & Co KG
- Belden Deutschland GmbH
- Huron Net Works
- Ametek Automation & Process Technologies
- Real Time Automation, Inc.
- Pepperl+Fuchs
- ASCO Numatics
- Horner Electric
- AVG Automation (Uticor)
- Online Development, Inc. (OLDI)
- Mitsubishi Electric Automation, Inc.
- MKS Instruments, Inc.
- SWCC Corporation
- Beckhoff Automation
- Molex Incorporated



- To provide education to vendors around the world, ODVA held several online training courses
- Thanks to our ODVA Designated Trainers for their hard work!



Global Activities



CIP Safety Protocol Training
Session 3: CIP Safety Details

Virtual Training Courses

ODVA

Maximizing Your Device

Filip Zembok (Rockwell Automation)

ODVA

EtherNet/IP

Quick Start for Vendors

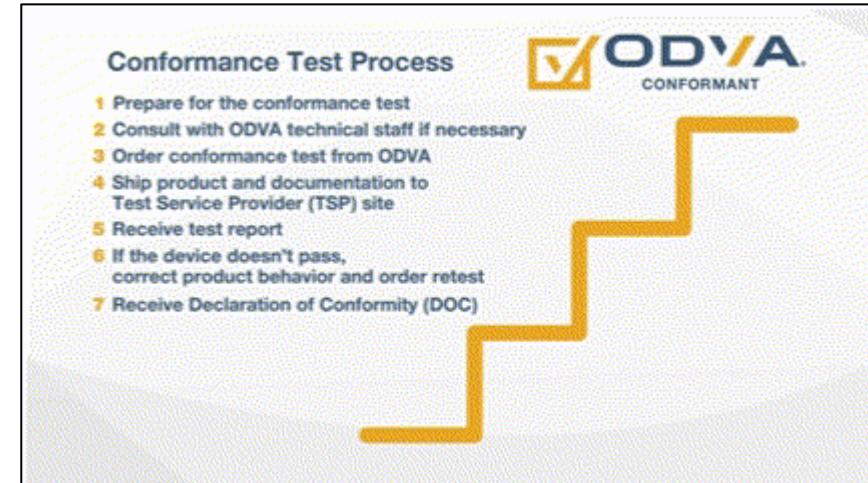
ODVA

David Clegg
Andrew Koenig Esposito
Stacy Amt...
View all

Matthew Frazee
Michelle...
EL
SA
SC
HH
DB
SV
SC
HH
DB
SV

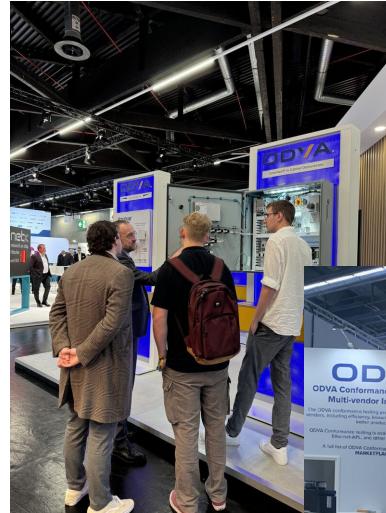
Global Activities

- ODVA launched two videos globally: one on EtherNet/IP for the process industries and one on the importance of conformance testing



Visit www.odva.org to watch and share!

- In Europe, ODVA highlighted the benefits of EtherNet/IP, including EtherNet/IP for In-Cabinet, 5G and wireless, CIP Security and SPE including APL at:
 - Hannover Messe 2024
 - ACHEMA 2024
 - SPS 2023 and 2024

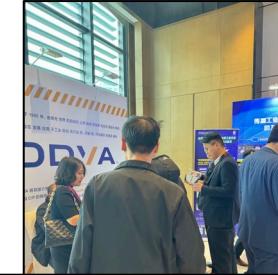


Global Activities



Global Activities

- In China, TAG China featured EtherNet/IP at Gongkong's forums, at the Control Engineering China annual meeting, and at IAS



Global Activities

- In Korea, TAG Korea held its first EtherNet/IP and Ethernet-APL event and published articles in local media



Global Activities

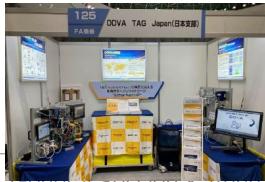
- In Japan, TAG Japan held several seminars, interoperability events, and participated in multiple exhibitions, including IIFES

Exhibition

IIFES2024(Jan 2024)



Okayama Technology exhibition (Nov. 2023)



Industrial open network exhibition (Jul. 2024)

1296 people visited!
Booth:892 people
Online:404 people

ODVA HQ
President : Al-san
Vice president : Adrienne-san
Market Leader : Steve-san
Joined!

Seminar

Held 6 + Planned 2 seminars since Oct 2023.

Real Seminar



Live streaming



Real Exhibition



Inter operability test

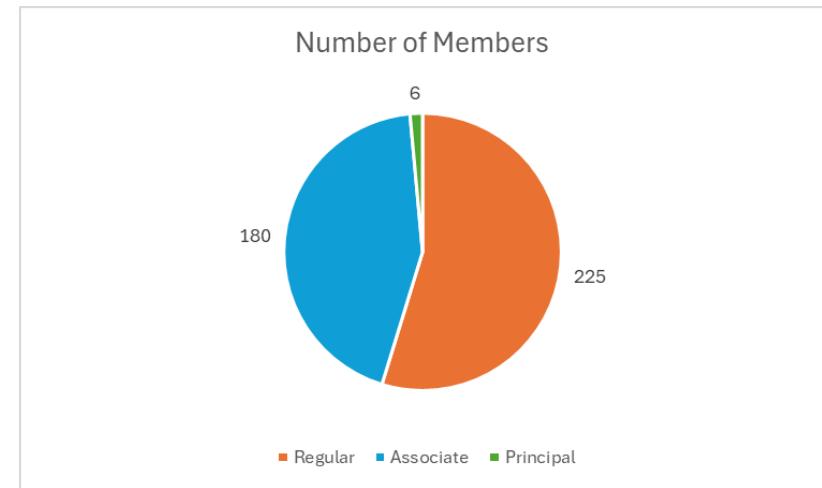
18 devices from 12 company are connected each other
(Dec. 2023)



- ODVA continued to add new Members from around the world with over 415 Members as of today
- Over 70 new vendor IDs have been issued since the last Annual Meeting to companies beginning to make EtherNet/IP products



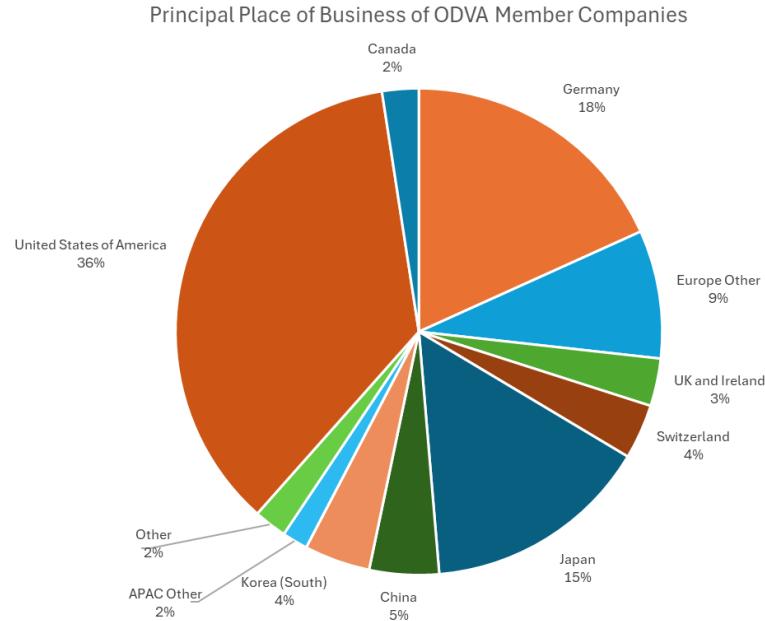
Growth over Past Term



Type	Number of Members
Regular	225
Associate	180
Principal	6

Growth over Past Term

Mix of Membership by Principal Place of Business, as of December 31, 2024



Country or Region	Principal Place of Business of ODVA Member Companies
Germany	75
Europe Other	35
UK and Ireland	13
Switzerland	15
Japan	62
China	19
Korea (South)	18
APAC Other	7
Other	9
United States of America	148
Canada	10



Looking Forward

- ODVA continues to drive education and awareness of the application of our technologies, as well as improve internal structures
 - New Association Management System that we announced that was contracted will be going online in 2025! We will provide more information and training when the launch date approaches.
 - Educational video on SPE in the works
 - Hands on training being developed
 - Full marketing audit to be commissioned
 - Licensing process under review
 - And more!

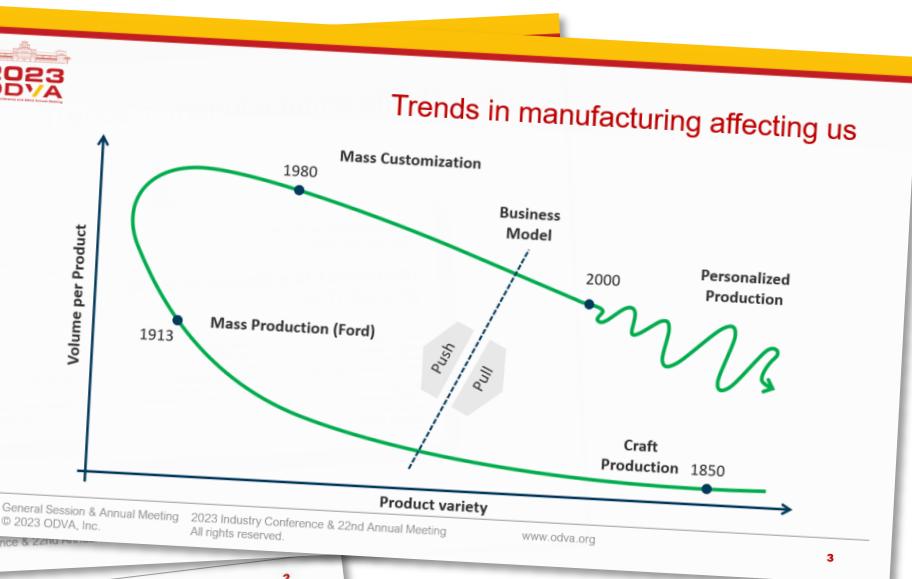


Update on ODVA Technical Activities

Joakim Wiberg
Director of Technology
ODVA



Trends in manufacturing are still affecting us



SIG Work Summary

- A total of 53 Specification Enhancements (SEs) and Technical Document Enhancements (TDEs)
- Two publication cycles in 2024
- One publication cycle to date in 2025 (will be complete in April)

- A total of 12 volume revisions

Accomplishments since 22nd Annual Meeting

- Redefined the scope of xDS
- Delivering CIP Security config with a file (making it easier to configure CIP Security device)
- Initiated work with IPv6
- Expanding process profiles (temperature and level)
- Extend Concurrent Connections to CIP Safety (serving process safety)
- Ensure compliance with upcoming safety requirements (ensure compliance with normative requirements in IEC61784-3 Edition 5)
- Creation of installation manuals for In-Cabinet EtherNet/IP
- Multiple updates, corrections, and clarifications (device-based firewall, concurrent connections, In-cabinet, CIP Motion, process diagnostics,....)

- The xDS project was initiated with a vision to modernize device descriptors
- In 2023, the TRB revisited the scope of the project, and developed a proposal to the Board
- The Board requested the TRB to develop a plan to address the most urgent issues
 - Minimum bar requirements to meet market needs
- The project has been divided into two phases:
 - Phase 1 Initiatives:
 - Enhancing security
 - Defining minimum support required for EDS consumers
 - Specifying Metadata for modern workflows
 - Phase 2 Initiatives:
 - Identify and prioritize additional gaps with EDS and the use of EDS.
 - E.g. configurable assemblies, modular devices, parameter dependencies, etc
 - Improve device description file accessibility.
 - Create an online repository for EDS and xDS files

- Phase 1 Initiatives:
 - Enhancing security (Lead: EtherNet/IP System Arch SIG)
 - A technical paper was presented at this conference
 - Defining minimum support required for EDS consumers (Lead: CIP System Arch SIG)
 - Control vendors and device vendors manned the SIG with relevant resources
 - The SIG is currently working on a CIPSE
 - Specifying Metadata for modern workflows (Lead: Common Industrial Cloud Interface SIG)
 - Papers have been presented at previous and on conference
 - Active discussions within the SIG

In Process and Proposed Plans for Next 12-18 Months

- Enhancing device's usability, integration, and functionality (Metadata for CIP paper)
- Complete xDS Phase 1
- Explore inclusion of new transition media – SPE and Gigabit
- State of the art security – using the latest security transports, signing, and compliance with CRA (EDS signing paper and CRA paper)
- Investigate impact and implement use of IPv6 (IPv6 paper)
- Keeping CIP Safety relevant – conformance with new regulations and Closed Communication Systems

